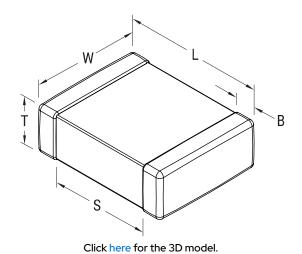




SMD Comm X8G HT150C Flex, Ceramic, 300 pF, 5%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



| General Information | |
|--------------------------|--|
| Series | SMD Comm X8G HT150C Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable |
| Features | High Temperature, Ultra-Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 15 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Dimensions | |
|------------|------------------|
| Chip Size | 1206 |
| L | 3.3mm +/-0.4mm |
| W | 1.6mm +/-0.35mm |
| т | 0.78mm +/-0.20mm |
| S | 1.5mm MIN |
| В | 0.6mm +/-0.25mm |
| | |

Packaging SpecificationsPackagingT&R, 330mm, Plastic TapePackaging Quantity10000

| Specifications | |
|--|--|
| Capacitance | 300 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | 5% |
| Voltage DC | 250 VDC |
| Dielectric Withstanding Voltage | 625 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | X8G |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 100 GOhms |

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